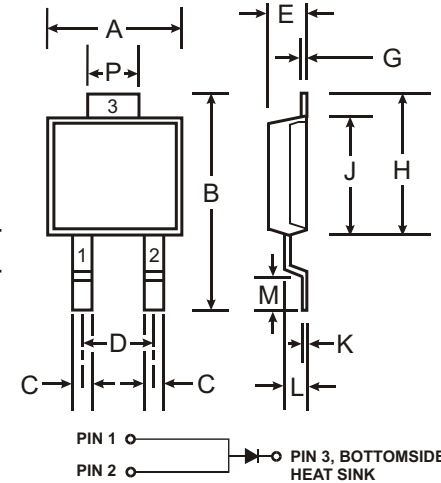


Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- High Surge Capability
- High Max Junction Temperature Rating
- Low Forward Voltage Drop
- Very Low Leakage Current
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Applications

Mechanical Data

- Case: POWERMITE®3, Molded Plastic
- Plastic Material: UL Flammability Classification Rating 94V-0
- Moisture sensitivity: Level 1 per J-STD-020A
- Terminals: Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Weight: 0.072 grams (approx.)
- Marking information: See sheet 3



Note: Pins 1 & 2 must be electrically connected at the printed circuit board.

POWERMITE®3		
Dim	Min	Max
A	4.03	4.09
B	6.40	6.61
C	.864	.914
D	1.83 NOM	
E	1.10	1.14
G	.173	.203
H	5.01	5.17
J	4.37	4.43
K	.173	.203
L	.71	.77
M	.36	.46
P	1.73	1.83
All Dimensions in mm		

Maximum Ratings @ T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	40	V
RMS Reverse Voltage	V _{R(RMS)}	28	V
Average Rectified Output Current (see also Figure 4)	I _O	10	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave Superimposed on Rated Load (JEDEC Method) @ T _C = 88°C	I _{FSM}	150	A
Typical Thermal Resistance Junction to Soldering Point	R _{θJS}	2.5	°C/W
Operating Temperature Range	T _J	-65 to +150	°C
Storage Temperature Range	T _{STG}	-65 to +150	°C

Electrical Characteristics @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 1)	V _{(BR)R}	40	—	—	V	I _R = 1mA
Forward Voltage (Note 1)	V _F	—	0.45 — 0.47	0.49 0.41 0.51	V	I _F = 8A, T _S = 25°C I _F = 8A, T _S = 125°C I _F = 10A, T _S = 25°C
Reverse Current (Note 1)	I _R	—	0.1 — 12.5	0.3 — 25	mA	T _S = 25°C, V _R = 35V T _S = 100°C, V _R = 35V
Total Capacitance	C _T	—	700	—	pF	f = 1.0MHz, V _R = 4.0V DC

Notes: 1. Short duration test pulse used to minimize self-heating effect.

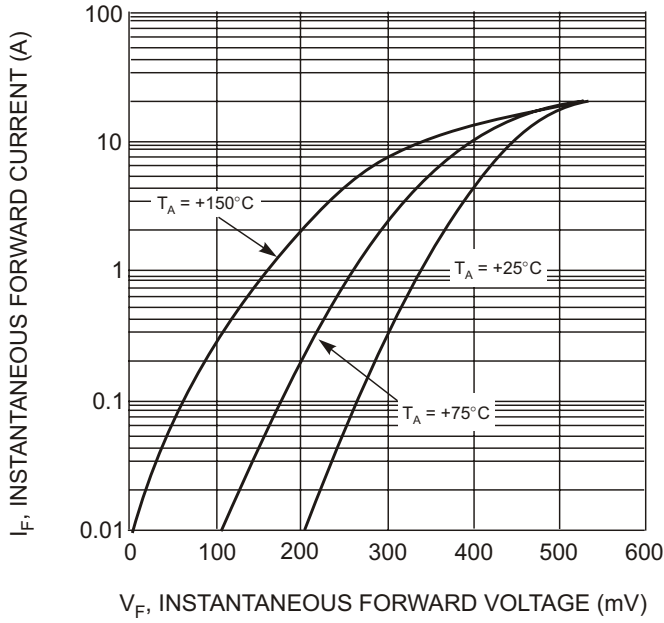


Fig. 1 Typical Forward Characteristics

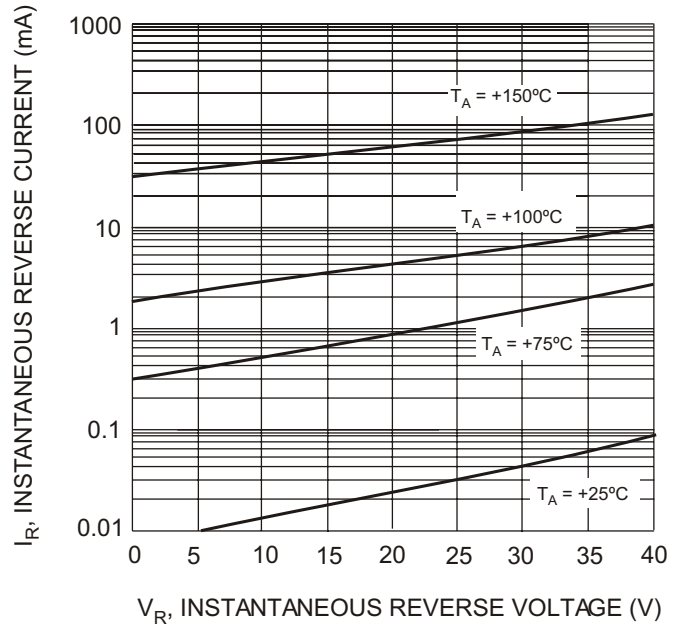


Fig. 2 Typical Reverse Characteristics

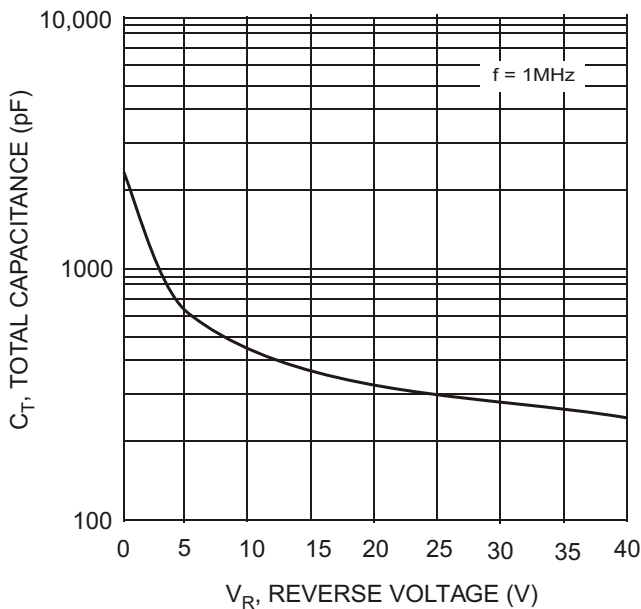


Fig. 3 Typical Total Capacitance vs. Reverse Voltage

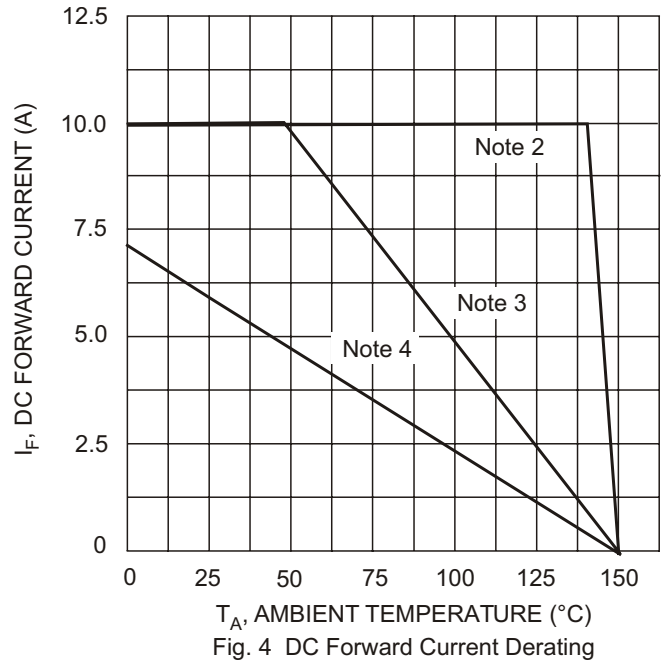


Fig. 4 DC Forward Current Derating

- Notes:
- $T_A = T_{\text{SOLDERING POINT}}, R_{\theta JS} = 2.5^\circ\text{C/W}, R_{\theta SA} = 0^\circ\text{C/W}.$
 - Device mounted on GETEK substrate, 2"x2", 2 oz. copper, double-sided, cathode pad dimensions 0.75" x 1.0", anode pad dimensions 0.25" x 1.0". $R_{\theta JA}$ in range of 15-30°C/W.
 - Device mounted on FR-4 substrate, 2"x2", 2 oz. copper, single-sided, pad layout as per Diodes Inc. suggested pad layout document AP02001 which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>. $R_{\theta JA}$ in range of 60-75°C/W.

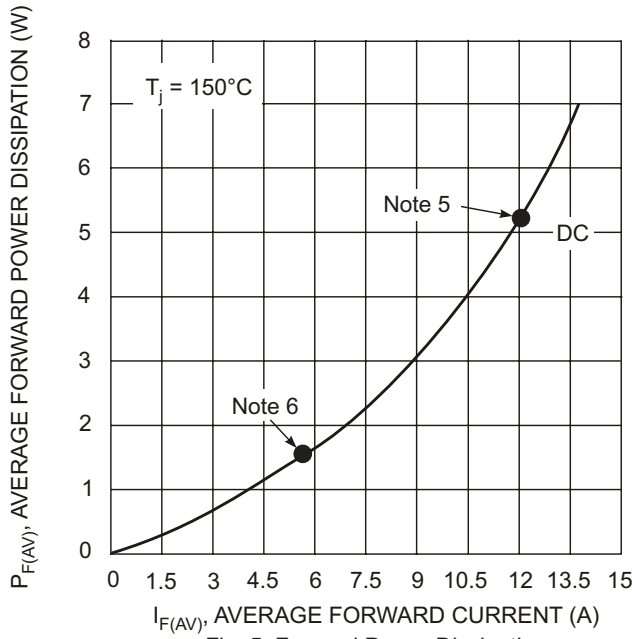


Fig. 5 Forward Power Dissipation

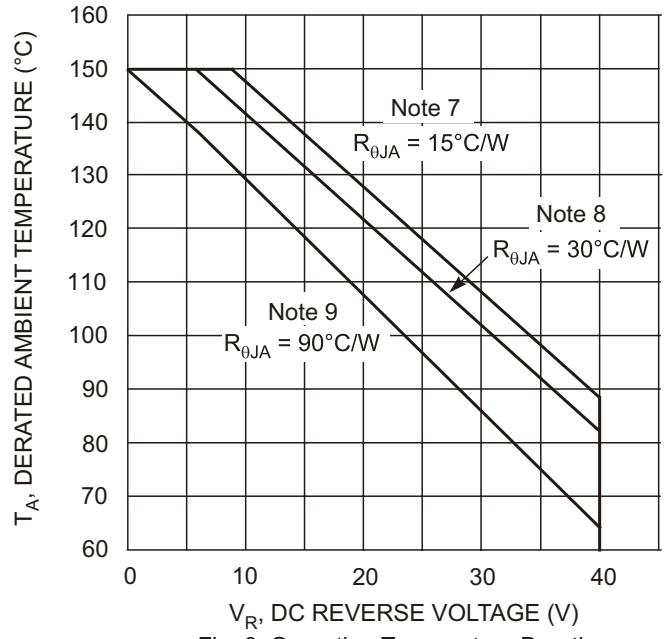


Fig. 6 Operating Temperature Derating

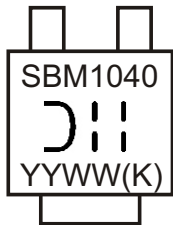
- Notes:
- Maximum power dissipation when device mounted on GETEK substrate, 2"x2", 2 oz. copper, double-sided, cathode pad dimensions 0.75" x 1.0", anode pad dimensions 0.25" x 1.0". $R_{\theta JA}$ in range of 15-30°C/W.
 - Maximum power dissipation when device mounted on FR-4 substrate, 2"x2", 2 oz. copper, single-sided, pad layout as per Diodes Inc. suggested pad layout document AP02001 which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>. $R_{\theta JA}$ in range of 60-75°C/W.
 - $R_{\theta JA} = 15^\circ\text{C/W}$ when mounted on 2"x2", single-sided, ceramic board with cathode pad dimensions 0.75"x1.0", anode pad dimensions 0.25"x1.0".
 - $R_{\theta JA} = 30^\circ\text{C/W}$ when mounted on 2"x2", single-sided, FR-4 board with cathode pad dimensions 0.5"x1.0", anode pad dimensions 0.5"x1.0", 2 oz. copper pads.
 - $R_{\theta JA} = 90^\circ\text{C/W}$ when mounted on 0.5"x0.625", single-sided, FR-4 board with minimum recommended pad layout.

Ordering Information (Note 10)

Device	Packaging	Shipping
SBM1040-13	POWERMITE®3	5000/Tape & Reel

Notes: 10. For Packaging Details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



SBM1040 = Product type marking code
 DII = Manufacturers' code marking
 YWW = Date code marking
 Y = Last digit of year ex: 2 for 2002
 WW = Week code 01 to 52
 (K) = Factory designator